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NOMURA(10) **Pub. No.: US 2023/0232527 A1**(43) **Pub. Date: Jul. 20, 2023**(54) **ELECTRONIC COMPONENT MODULE, AND
METHOD OF MANUFACTURING THE SAME**(52) **U.S. Cl.**CPC *H05K 1/0218* (2013.01); *H05K 1/181*
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A cap including a side wall portion having conductivity, a lid portion, a thin portion formed at least around the lid portion, and a beam portion supporting the lid portion is formed, an exposed component and a sealing component are mounted on a module substrate, the cap is mounted on the module substrate so as to surround an exposed component, the sealing component and the cap are sealed with a sealing resin, the lid portion is ground so as to reduce its thickness until the thin portion disappears, a shield layer is formed on an outer surface of the sealing resin and a side surface of the module substrate, a translucent adhesive sheet is attached on a top surface of the sealing resin, the beam portion is cut by laser through the adhesive sheet, and the adhesive sheet is peeled together with a lid portion.

[LID PORTION PEELING STEP]